

epoxy resin.

SUPPORT FOR THE AMENDMENTS

Applicants have amended Claim 22, to correct a typographical error so that it properly depends from Claim 21.

REMARKS

At the outset, Applicants' representative wishes to thank Examiners Cuneo and Patel for the helpful and courteous discussion held on February 13, 2003, during which the prosecution of the above-identified application was materially advanced. The following remarks will expand and summarize the issues discussed.

Present Claims 11-18 relate to a method for producing a multilayer printed-wiring board, comprising:

(1) plasma etching a layer of an insulating resin composition, to obtain a plasma-treated insulating layer; and

(2) forming a conducting layer on said plasma-treated insulating layer,

wherein said resin composition comprises a first resin and a second resin, and said first resin and said second resin have different plasma etching rates and said first resin and said second resin are not compatible with each other.

Present Claims 19 and 21-26 relate to multilayer printed-wiring boards prepared by such a method.

As explained during the above-noted discussion, one problem to be solved by the present invention may be described as how to ensure or improve the bonding strength between an insulating layer and the adjacent conducting layer(s) in a multilayer printed-